

Partial English-language translations of the references 1, 4 and 7

JP Hei.4-105590 U (from paragraphs 0007 to 0009)

[0007]

[Embodiment]

Hereinafter, an embodiment of the present invention will be explained with reference to the accompanying drawings. Figs. 1 and 2 show the embodiment of the invention.

[0008]

Fig. 1 is a schematic diagram showing the attachment state of the invention, in which an opening portion 10 is defined in the rear surface side of an electronic device 6, and a substrate 11 having a battery 2 for backing-up a memory is coupled through a connector 8 of this substrate to a connector 7 provided on a main substrate.

The opening portion 10 is closed by a lid portion 9 by means of screws after the completion of the connection.

[0009]

Fig. 2 is a schematic diagram showing the attachment relation between the memory back-up battery 2 and the substrate 11 and the attachment relation between the substrate 11 and the main substrate 3.

Electrodes 2a, 2b of the memory back-up battery 2 are soldered on a pattern surface 12, thereby to fix the memory back-up battery to the substrate 11. The connector 8 is electrically fixed to the pattern

surface of the substrate 11 by means of the soldering. The connector 7 is electrically fixed to the main substrate 3 by means of the soldering. Thus, the substrate 11 is coupled to the connector 7 through the connector 8 and so coupled to the main substrate 3.